

## LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

ATTY. DOCKET NO.

8317-091-999

APPLICATION NO.

09/903,064

APPLICANT

Small, et al.

FILING DATE

July 10, 2001

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 DEC 31 2001  
 TC 1/100

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
AA	✓	6,048,406	4/11/00	Misra et al.	134	200	
AB	✓	5,981,454	11/9/99	Small	510	175	
AC	✓	5,972,862	10/26/99	Torii et al.	510	175	
AD	✓	5,885,477	3/23/99	Rasmussen et al.	252	79.2	
AE	✓	5,792,274	8/11/98	Tanabe et al.	134	1.3	
AF	✓	5,709,756	1/20/98	Ward et al.	134	1.3	
AG	✓	5,705,089	1/6/98	Sugihara et al.	252	79.1	
AH	✓	5,672,577	9/30/97	Lee	510	175	
AI	✓	5,645,737	7/8/97	Robinson et al.	216	99	
AJ	✓	5,630,904	5/20/97	Aoyama et al.	438	669	
AK	✓	5,603,849	2/18/97	Li	216	99	
AL	✓	5,571,447	11/5/96	Ward et al.	510	206	
AM	✓	5,563,119	10/8/96	Ward	510	176	
AN	✓	5,560,857	10/1/96	Sakon et al.	510	175	
AO	✓	5,181,985	1/26/93	Lampert et al.	156	635	
AP	✓	5,129,955	7/14/92	Tanaka	134	2	
AQ	✓	4,770,713	9/13/88	Ward	134	38	
AR	✓	4,744,834	5/17/88	Haq	134	38	
AS	✓	4,508,591	4/2/85	Bartlett et al.	156	659.1	
AT	✓	4,428,871	1/31/84	Ward et al.	252	542	
AU	✓	4,403,029	9/6/83	Ward, Jr. et al.	430	258	
AV	✓	4,401,747	8/30/83	Ward, Jr. et al.	430	258	
AW	✓	4,395,479	7/26/83	Ward et al.	430	258	
AX	✓	3,592,773	7/13/71	Muller	252	79.3	

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
AY	✓	EP 0 662 705 B1	8/23/00	EPO				
AZ	✓	WO 98/36045	8/20/98	PCT				

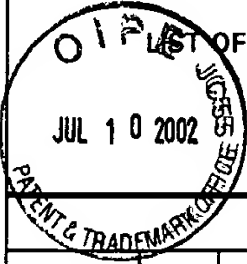
## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

BA	P.J. Ireland, "High Aspect Ratio Contacts: A Review of the Current Tungsten Plug Process," Thin Solid Films 304 (1997), pp. 1-12.
BB	C. Lee and S.C. Lee, "Effects of Plasma Treatments on the Erosion of TEOS-BPSG Films by Chemical Etchants," Solid State Electronics, Vol. 41, No. 6, pp. 921-923 (1997).
BC	M.R. Baklanov, et al., "Applicability of HF Solutions for Contact Hole Cleaning on Top of $\text{Si}_2\text{N}_2$ Electrochemical Society Proceedings, Vol. 97-35, pp. 602-609 (1998).
BD	C. Rafols, et al., "Ionic Equilibria in Aqueous Organic Solvent Mixtures: The Equilibria of HF in an Ethanol + Water Mixture Used for Cleaning Up Semiconductors," J. Electroanalytical Chem. 433, pp. 77-83 (1997).
BE	K. Ueno, et al., "Cleaning of $\text{CHF}_3$ Plasma-Etched $\text{SiO}_2/\text{SiN}/\text{Cu}$ Via Structures with Dilute Hydrofluoric Acid Solutions," J. Electrochem. Soc., Vol. 144, No. 7, pp. 2565-2572 (July 1997).
BF	T. Kujime, et al., "The Cleaning of Particles From Si Water Surface by Fluorine Solution Excited by Megasonic," Proceedings of the 1996 Semi. Pure Water and Chemicals, pp. 245-256 (1996).
BG	P. Singer, "Wafer Cleaning: Making the Transition to Surface Engineering," Semiconductor Int'l, p. 88-92 (Oct. 1995).
BH	M. Liehr and S.R. Kasi, "HF and UV-Ozone Integrated Wafer Preclean: Chemistry and Effects on Thermal Gate Oxide," 1991 Int'l Conf. on Solid State Devices and Materials, Yokohama, pp. 484-486 (1991).
BI	L.O. Ohman and S. Sjöberg, "Equilibrium and Structural Studies of Silicon(IV) and Aluminum(III) in Aqueous Solution. Part 9. A Potentiometric Study of Mono- and Poly-nuclear Aluminum(III) Citrates," J. Chem. Soc. Dalton Trans., pp. 2513-2517 (1983).


EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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U.S. PATENT DOCUMENTS						
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	5,928,430	7/27/99	Ward et al.			

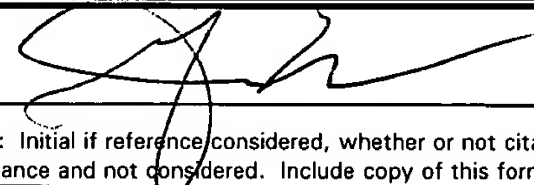
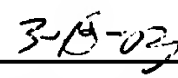
  

FOREIGN PATENT DOCUMENTS							
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						YES	NO

OTHER REFERENCES <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>		

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